



Future Normal in Semiconductor

2025년 2월 14일(금), 15:10-17:10

Room C(컨벤션홀 L), 5층

D. Thin Film Process Technology 분과

069_[FC3-D] Atomic Layer Deposition - III

좌장: 한정환 교수(서울과학기술대학교), 임태용 교수(세종대학교)

<p>FC3-D-1 15:10-15:25</p>	<p>Area-selective Atomic Layer Deposition of Ruthenium Thin Films via Atmospheric Pressure Plasma Technology Dahui Jeon^{1,2} and In-Hwan Baek^{1,2} ¹Department of Chemical Engineering, Inha University, ²Program in Semiconductor Convergence, Inha University</p>
<p>FC3-D-2 15:25-15:40</p>	<p>Inherent Area-Selective Deposition of Low-resistivity Molybdenum Carbide Films by Thermal Atomic Layer Deposition Ji Sang Ahn and Jeong Hwan Han Department of Materials Science and Engineering, Seoul National University of Science and Technology</p>
<p>FC3-D-3 15:40-15:55</p>	<p>Theoretical Development of Area-Selective Atomic Layer Deposition Process of Ruthenium via Reduction of Interfacial Oxidation Iaan Cho^{1,2}, Eun-Hyoung Cho³, Dabin Kong⁴, Youngchul Leem³, Young Min Lee³, Miso Kim¹, Chi Thang Nguyen⁴, Jeong Yub Lee³, Han-Bo-Ram Lee⁴, and Bonggeun Shong¹ ¹Hongik University, ²Yonsei University, ³SAIT, ⁴Incheon National University</p>
<p>FC3-D-4 15:55-16:10</p>	<p>In-Situ Hydrogen Gas Annealing in ALD Reactor for Improved Quality of Cobalt Thin Film Jaeseong Pyo, Giryun Hong, Jongseo Park, Bohyeon Kang, Jehyun An, Beomjoo Ham, Sung-Min Ahn, and Rock-Hyun Baek Department of Electrical Engineering, POSTECH</p>
<p>FC3-D-5 16:10-16:25</p>	<p>Development of Atomic Layer Etching of ZrO₂ Thin Films Using NF₃ Plasma and TiCl₄ Haram Yang¹, Hyeongjun Kim², and Woongkyu Lee^{1,2} ¹Department of Materials Science and Engineering, Soongsil University, ²Department of Green Chemistry and Materials Engineering, Soongsil University</p>



Future Normal in Semiconductor

<p>FC3-D-6 16:25-16:40</p>	<p>Growth Characteristics of ZrO_2, HfO_2, and In_2O_3 Deposited by Liquid Injection Atomic Layer Deposition Soon-Kyeong Park¹, JunHee Cha², and Il-Kwon Oh^{1,2} ¹Department of Intelligence Semiconductor Engineering, Ajou University, ²Department of Electrical and Computer Engineering, Ajou University</p>
<p>FC3-D-7 16:40-16:55</p>	<p>High Temperature TiN Atomic Layer Deposition Using N-containing Reactants Hyewon Park, Yoonseo Choi, and Han-Bo-Ram Lee Department of Materials Science and Engineering, Incheon National University</p>
<p>FC3-D-8 16:55-17:10</p>	<p>Advanced Atomic Layer Deposition: Enhanced Oxidation Resistance and Film Properties of SiN_x Films by Using Highly Reactive N Sources and Discrete Feeding Method Ui Hyeon You, Jae Chan Park, and Tae Joo Park Department of Materials Science and Chemical Engineering, Hanyang University</p>